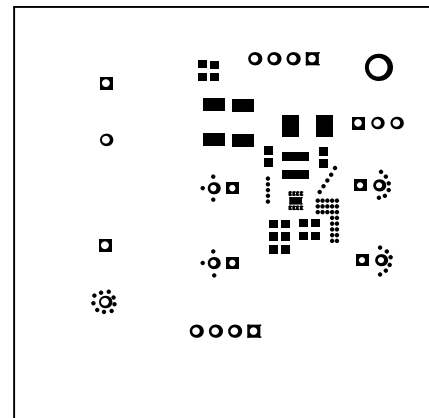
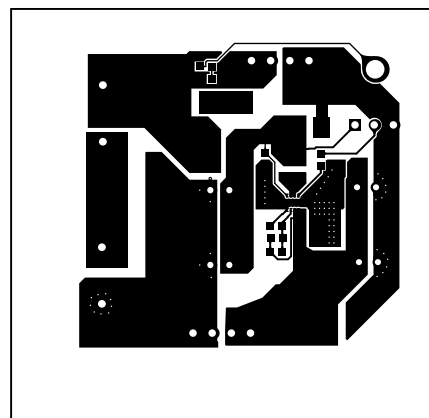


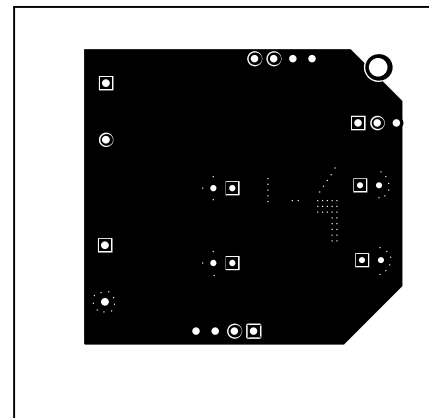
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01387		
PLOT NAME = Top Overlay	GENERATED : 12/12/2016 7:52:20 PM	TEXAS INSTRUMENTS	



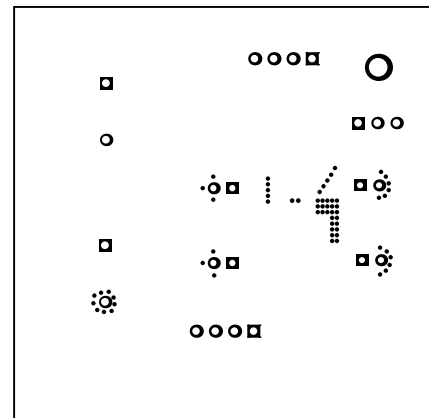
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01387		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2016 7:52:21 PM	TEXAS INSTRUMENTS	



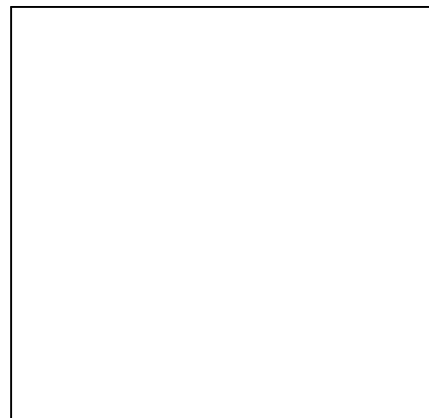
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01387		
PLOT NAME = Top Layer	GENERATED : 12/12/2016 7:52:24 PM	TEXAS INSTRUMENTS	



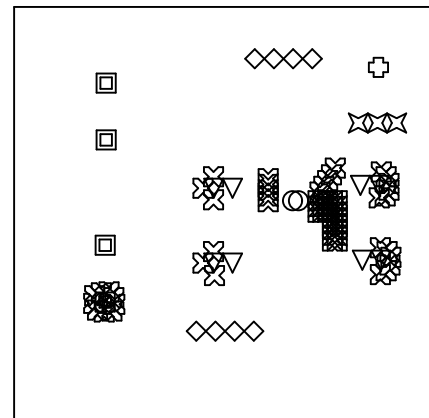
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01387		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2016 7:52:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01387		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2016 7:52:30 PM	TEXAS INSTRUMENTS	

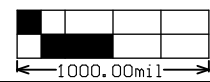
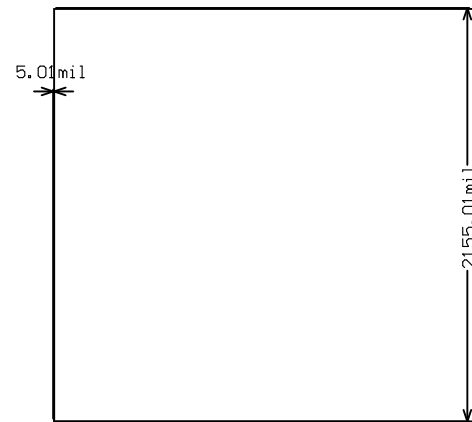


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01387		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2016 7:52:34 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	2	7.87mil (0.200mm)	PTH	Round
⊠	62	8.00mil (0.203mm)	PTH	Round
▽	8	33.00mil (0.838mm)	PTH	Round
◇	8	40.00mil (1.016mm)	PTH	Round
⊠	3	40.16mil (1.020mm)	PTH	Round
■	4	41.34mil (1.050mm)	PTH	Round
⊕	1	98.43mil (2.500mm)	PTH	Round
88 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01387		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2016 7:52:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01387	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01387		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2016 7:52:39 PM	TEXAS INSTRUMENTS	

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